

Catalog # 72-0751 Hafnium(IV) chloride, sublimed grade (99.9+%-Hf, <1.0% Zr)

HfCl₄

Thermal Behavior:

- Sublimation at 320°C
- Melting point: 432°C (Triple point; sealed tube)
- Vapor pressure 1 Torr at 190°C; Tables are available in [1]

Technical Notes:

1. ALD/CVD precursor for hafnium thin film deposition

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
HfO ₂	ALD	200°C	1.5 Torr	H ₂ O	300°C	2
	ALD	-	2-6 Torr	H ₂ O	200-300°C	3
	ALD	140°C	-	H ₂ O	180°C	4
	ALD	170°C	-	H ₂ O	250°C	5
	AP-ALD	160°C	AP	O ₂	300°C	6
	ALD	165-190°C	1 Torr	O ₃	200-250°C	7
HfS ₂	CVD	300°C	-	S Powder	950°C	8
	ALD	125-130°C	3.75 Torr	H ₂ S	400°C	9
Hf _x Al _y O _z	ALD	-	7.5 Torr	Al(OEt) ₃	400°C	10
Hf _x Al _y C _z	ALD	160°C	-	TME	270°C	11
Hf _x Si _y O _z	ALD	180°C	-	Si(OC ₂ H ₄) ₄ ; H ₂ O	300°C, 500°C	12
Hf _x Ca _y O _z	ALD	160°C	-	Ca(Cp ³ⁱ) ₂ ; H ₂ O	300°C	13
Hf _x Ti _y O _z	ALD	170°C	4 Torr	TiCl ₄ ; H ₂ O	300°C	14
Hf _x Y _y O _z	ALD	-	0.5 Torr	Y(Cp*) ₃ ; H ₂ O	260-420°C	15
Gd:HfO ₂	ALD	-	-	Gd(PrCp) ₃ ; H ₂ O	300°C	16
Pr:HfO ₂	ALD	-	1.5 Torr	Pr(THMD) ₃ ; O ₃	250-350°C	17

References:

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